



**TARGET THICKNESS: 0.047"**  
**NUMBER OF LAYERS: 08**

# MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

<b>8 Layer StackUp (0.047") L08-047-1ozHoz</b>		<b>Thickness (inches)</b>
<b>Layer 1</b>	<b>.5 oz foil plated to approximate* thickness 0.0017"</b>	0.0017
Prepreg	Bonding ply (3x1080) Average Dielectric Constant 4.5	0.0066
<b>Layer 2</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
<b>Layer 3</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x1080) Average Dielectric Constant 4.5	0.0044
<b>Layer 4</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
<b>Layer 5</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x1080) Average Dielectric Constant 4.5	0.0044
<b>Layer 6</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.005
<b>Layer 7</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (3x1080) Average Dielectric Constant 4.5	0.0066
<b>Layer 8</b>	<b>.5 oz foil plated to approximate* thickness 0.0017"</b>	0.0017
<b>"Thickness does not include soldermask or surface finish"</b>		<b>0.0488</b>

**NOTES:**